

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: S.-F. WANG, ET AL.
Application No.: 10/087,432
Filed: MARCH 1, 2002
For:

Group No.: 2827
Examiner: J. MITCHELL

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

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37 C.F.R. SECTIONS 1.52(d), 1.55(a), 1.69

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(Statement of Accuracy of Translation--page 1 of 2) 5-3

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The document for which the attached English translation is being submitted is

PATENT APPLICAITON CN 090104684 OF MARCH 1, 2001

(check and complete, if applicable)

[X] This foreign language document was filed in the PTO on OR ABOUT APRIL 24, 2002.

Date: 2003. 10. 30 (x)

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In re: Sung-Fei WANG, et al.

Serial No.: 10/087,432 Group 2827

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For: STACKED SEMICONDUCTOR CHIP PACKAGE

STATEMENT OF ACCURACY OF A TRANSLATION; SPECIFICATION

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